



60V N-Channel Enhancement Mode MOSFET

Voltage

60 V

Current

33 A

Features

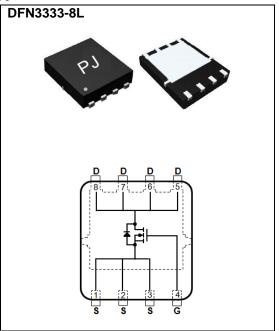
- $R_{DS(ON)}$, $V_{GS}@10V$, $I_D@16A<17m\Omega$
- $R_{DS(ON)}$, $V_{GS}@4.5V$, $I_{D}@8A<20m\Omega$
- Advanced Trench Process Technology
- High density cell design for ultra low on-resistance
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

Mechanical Data

• Case: DFN3333-8L Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.0002 ounces, 0.006 grams



Maximum Ratings and Thermal Characteristics (T_A=25 °C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		V_{DS}	60		
Gate-Source Voltage		V_{GS}	<u>+</u> 20	V	
Continuous Drain Current (Note 4)	T _C =25°C	I _D	33	А	
	T _C =100°C		21		
Pulsed Drain Current (Note 1)	T _C =25°C	I _{DM}	132		
Power Dissipation	T _C =25°C	Po	40	W	
	T _C =100°C		16		
Continuous Drain Current	T _A =25°C	I _D	7.3	А	
	T _A =70°C		5.9		
Power Dissipation	T _A =25°C	Б.	2.0	14/	
	T _A =70°C	Pb	1.3	W	
Single Pulse Avalanche Energy (Note 6)		E _{AS}	45	mJ	
Operating Junction and Storage Temperature Range		T _J ,T _{STG}	-55~150	°C	
Typical Thermal Resistance (Note 4,5)	Junction to Case	$R_{ heta JC}$	3.1	°C/W	
	Junction to Ambient	$R_{\theta JA}$	62.5		

• Limited only By Maximum Junction Temperature





Electrical Characteristics (T_A=25 °C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS	
Static							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	60	-	-	V	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{D}=250uA$	1	1.7	2.5		
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =16A	-	13	17	mΩ	
		V_{GS} =4.5V, I_D =8A	-	16	20		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V	-	-	1	uA	
Gate-Source Leakage Current	I _{GSS}	V _{GS} = <u>+</u> 20V, V _{DS} =0V	-	-	<u>+</u> 100	nA	
Dynamic (Note 5)			_				
Total Gate Charge	Q_g	V _{DS} =30V, I _D =10A, V _{GS} =4.5V ^(Note 1,2)	-	13.5	-	nC	
Gate-Source Charge	Q_gs		-	4.8	-		
Gate-Drain Charge	Q_{gd}		-	4.9	-		
Input Capacitance	Ciss	V _{DS} =25V, V _{GS} =0V, f=1MHZ	_	1574	-	pF ns	
Output Capacitance	Coss		-	118	-		
Reverse Transfer Capacitance	Crss	I= IIVII IZ	-	77	-		
Turn-On Delay Time	td _(on)	\/ 45\/ 40	-	11	-		
Turn-On Rise Time	t _r	V_{DD} =15V, I_{D} =1A, V_{GS} =10V, R_{G} =6 Ω (Note 1,2)	-	11	-		
Turn-Off Delay Time	td _(off)		-	35	-		
Turn-Off Fall Time	t _f		-	8.1	-		
Drain-Source Diode							
Maximum Continuous Drain-Source	I _S		-	-	33	А	
Diode Forward Current	IS						
Reverse Recovery Time	V_{SD}	I _S =1A, V _{GS} =0V	-	0.68	1	V	

NOTES:

- 1. Pulse width<300us, Duty cycle<2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C. Ratings are based on low frequency and duty cycles to keep initial T_J =25°C.
- 4. The maximum current rating is package limited.
- 5. Rejah is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch² with 2oz.square pad of copper.
- 6. The test condition is L=0.1mH, I_{AS} =30A, V_{DD} =25V, V_{GS} =10V, Starting T_{J} =25 $^{\circ}$ C.
- 7. Guaranteed by design, not subject to production testing.





TYPICAL CHARACTERISTIC CURVES

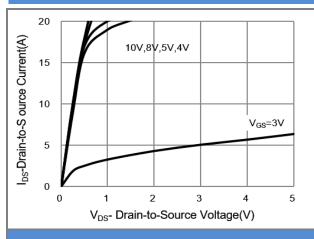


Fig.1 On-Region Characteristics

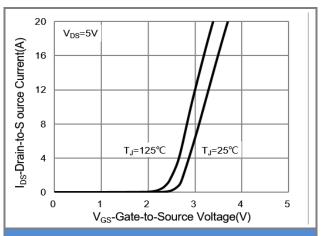


Fig.2 Transfer Characteristics

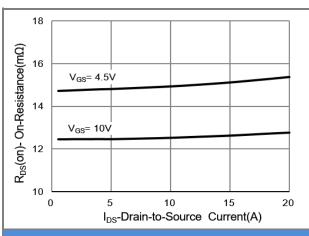


Fig.3 On-Resistance vs. Drain Current

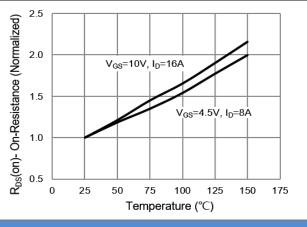
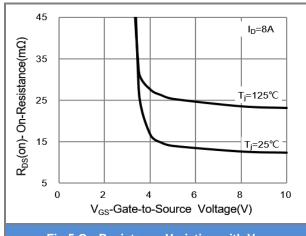


Fig.4 On-Resistance vs. Junction temperature





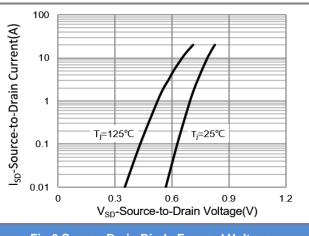


Fig.6 Source-Drain Diode Forward Voltage





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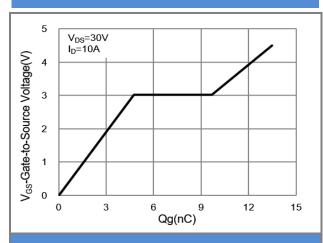


Fig.7 Gate-Charge Characteristics

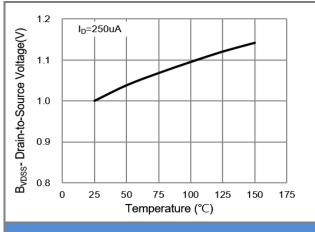


Fig.8 Breakdown Voltage Variation vs. Temperature

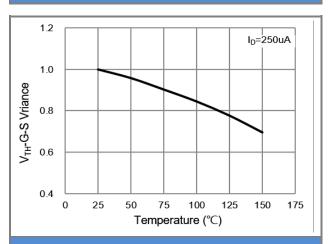


Fig.9 Threshold Voltage Variation with Temperature

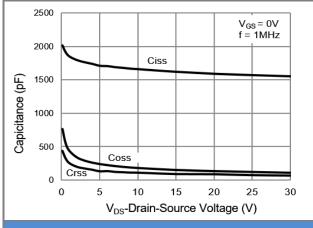
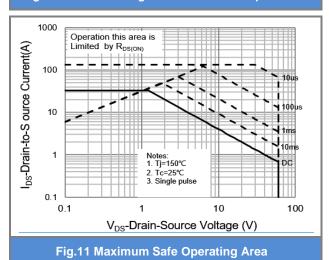


Fig.10 Capacitance vs. Drain-Source Voltage







TYPICAL CHARACTERISTIC CURVES

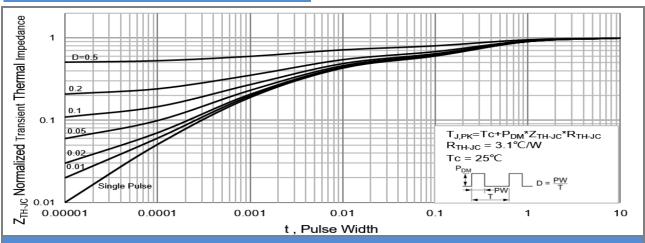


Fig.12 Normalized Transient Thermal Impedance vs. Pulse Width

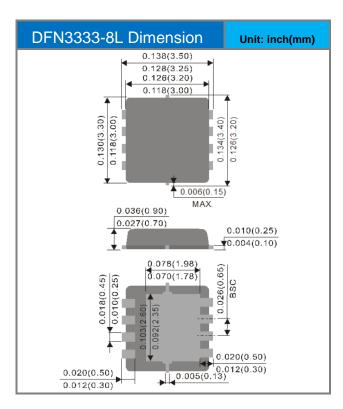


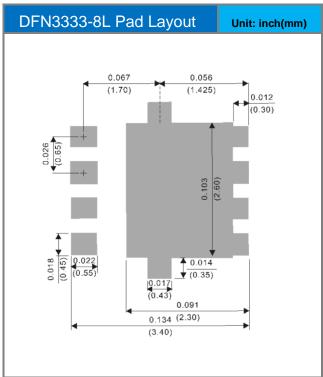


Part No Packing Code Version

Part No Packing Code	Package Type	Packing Type	Marking	Version
PJQ4464AP_R2_00001	DFN3333-8L	5K pcs / 13" reel	4464	Halogen free

Packaging Information & Mounting Pad Layout









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